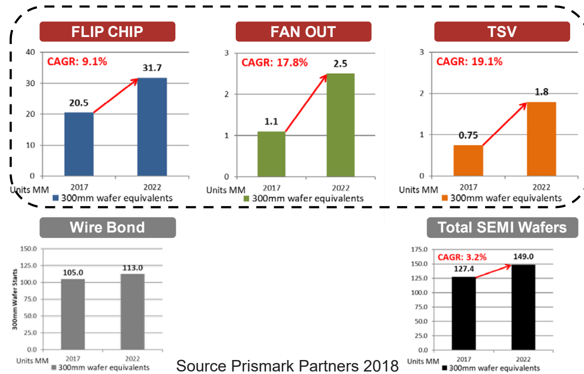
Growth rate forecasts for 2017 - 2022 for interconnects by technology in 300 mm equivalent wafer starts



Source Prismark Partners 2018

Serving our customers in Asia, Europe and North America for over 15 years

ASM NEXX USA

- 900 Middlesex Turnpike, Building 6
- Billerica MA 01821-3929
- TEL 978-338-2800
- FAX 978-338-2801

NEXXSales@ASMPT.com

www1.asmpacific.com/en/products?equipment=90

Metal Deposition Solutions

ASM NEXX equipment processes the fastest growing, highest technology interconnects in the advanced packaging market

PVD Wafer	ECD Wafer	ECD Panel
Apollo	**Stratus™**	**Stratus™**

- ASM NEXX, Inc. is a systems engineering integration company in a micro-scale environment
- ASM NEXX, Inc. brings together hardware and software to process metals under the tighest specifica-tions at the micron scale
- ASM NEXX equipment processes wafers, panels and other substrates for semiconductor manufacturing leaders 24-hours a day, 7-days a week, 365-days a year

ASM NEXX Singapore
ASM Technology Singapore

- 2 Yishun Avenue 7, Singapore 768924
- NEXXSingapore@ASMPT.com

ASM NEXX China
ASM Microelectronic Technical Services 2/F

- No. 55 Zu Chong Zhi Road, Lot 1505
- Shanghai Zhang Jiang Hi-Tech Park
- Shanghai 201203
- NEXXChina@ASMPT.com

ASM NEXX Korea
ASM Pacific(Hong Kong) Limited Korea Branch

- (Deungchon-dong), 4F., 408, Hwagok-ro, Gangseo-gu
- Seoul, 07548,Korea
- NEXXKorea@ASMPT.com

ASM NEXX Taiwan

- 20F.-5, No.32, Gaotie 2nd Rd,
- Zhubei City, Hsinchu Country 302,
- Taiwan R.O.C.
- NEXXTaiwan@asmpt.com

ASM NEXX Japan
ASM Assembly Technology

- 5F TCKW F-Bidg, 1-7-18, Nishiki-cho, 190-0022, Tachikawa-shi,
- Tokyo, Japan
- NEXXJapan@asmpt.com

ASM NEXX Europe
ASM Assembly Systems

- Rupert-Mayer-Strasse 44
- 81379 Munich, Germany
- NEXXEurope@asmpt.com

©2019

For wafers, panels & more

Physical Vapor Deposition

Apollo Wafer Level

More flexible features

- Highest flexibility sputtering tool on the market in the smallest footprint
- Bridge capability for 100, 150, 200 & 300 mm wafers as well as package level
- Configurable for up to 5 metal targets
- Safe wafer handling for various fragile substrates, thin and bowed wafer types

Electro-chemical Deposition

Stratus™ Wafer Level

Safer substrate handling

- Highest flexibility plating tool on the market
- Bridge capability for 100, 150 & 200 mm or 200 & 300 mm wafers
- Processes up to 6 chemistries at one time
- Safe wafer handling for various fragile substrates, thin and bowed wafer types

Electro-chemical Deposition

Stratus™ Panel Level

Higher precision technology

- Highest wafer scale precision solution on the market for panels
- Handles panel sizes up to 510 x 515 mm
- Processes up to 5 chemistries at one time
- Safe wafer handling for various fragile substrates, thin and bowed wafer types

With more applications ...

The right choice for you and your customers

Apollo Wafer Level

- Under bump metallization for bumping and redistribution layers
- Interposers, fan out and TSV
- RF Filter wafer level chip scale processing
- Power Devices (FSM & BSM)

Stratus™ Wafer Level

- Wafer bumping (RDL, Cu Pillar, Microbump and Au)
- Interposers, fan out and TSV
- RF Filter wafer level chip scale processing
- Power Devices (FSM & BSM)

Stratus™ Panel Level

- Fan out panel scale plating
- Embedded interconnections in substrate

©2019